


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 21 January 2019 [Approved on 13 June 2019, 15:53 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.95000%	Gold	7440-57-5	0.06000%
			BETA-ALUMINUM OXIDE	1344-28-1	0.55000%
			Nickel	7440-02-0	1.72000%
			Silicon Dioxide	7631-86-9	5.70000%
			Silicon	7440-21-3	91.97000%
Die attach	Lead and Lead alloys	2.55000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	15.66000%	Carbon black	1333-86-4	0.30000%
			Antimony oxide	1309-64-4	0.80000%
			Phenol, 4,4'-(1-methylethylidene)bis[2,6-dibromo-, polymer with (chloromethyl)oxirane	40039-93-8	0.99000%
			resin	9003-35-4	5.00000%
			Epoxy resin ERL-2795	25068-38-6	27.61000%
	Fused Silica	60676-86-0	65.30000%		
Leadfinish	Tin plating	1.36000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	79.48000%	Phosphorus	7723-14-0	0.02000%
			Iron	7439-89-6	0.10000%
			Copper	7440-50-8	99.88000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-218AB	Diode SMD	2.9	g

Based on the information currently available, these substances do not pose any risk if the articles are used as intended (including disposal). Additional information is not necessary to allow safe use of the article.